## $CF_4+O_2/N_2$

## Optical Diagnostics of $N_2$ Gas Added $CF_4+O_2$ Plasma and Study on $UO_2$ Etching Reaction

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17

(KAERI)

150

 $CF_4$ ,  $O_2$ OES(Optical Emission Spectroscopy) RF(Radio Frequency) F 가 , CF<sub>4</sub> 4:1 가 가 CF<sub>4</sub>+O<sub>2</sub> 가 5 % 가 F . OES ,  $CF_4+O_2$ F  $N_2$ 가 가 가 F

## **Abstract**

A diagnosis of optical properties of  $N_2$  added  $CF_4+O_2$  plasma under RF power is carried out by using OES (Optical Emission Spectroscopy) along with the investigation of decontamination rate enhancement for the development of nuclear fuel materials decontamination technique. In this study experimental variables are the ratio of  $N_2$  to  $CF_4+O_2$  gas. The ratio,  $CF_4/O_2$ , is maintained to be four since it is reported to be the optimum in the binary gas mixture system for the process. It is found that when small amount of  $N_2$  is added to  $CF_4+O_2$  plasma the decontamination rate can be enhanced almost twice compared to that of  $CF_4+O_2$  plasma without  $N_2$  gas. The optimum ratio of  $N_2$  to  $CF_4+O_2$  turns out to be 5% based on the gas volume. Optical emission spectra focused on F atom density is thoroughly analyzed to support the results since the fluorine atom is believed to play a significant role in the chemical etching of  $UO_2$  in the mixture gas plasma. It is revealed that fluorine atom density reaches maximum at the optimized  $N_2/CF_4/O_2$  plasma, and the etching rate of  $UO_2$  is closely proportional to the F atom density.

I.

(DUPIC)

TRU( ) 0.1%

プト (1,2). 1%

2 . 2

PUREX

TRU .

. 가

가 radical, ion . , , 가

```
가
                                                                                            CF_4:O_2
                                                                                                          가
                                                                           가
4:1
                                 CF<sub>4</sub>+O<sub>2</sub> plasma
                                                             N_2
                                                                                                        OES
                                                   F
                                          etchant
II.
                                              가
 CF_4+O_2
                               N_2
                              CF<sub>4</sub>, O<sub>2</sub>
                                                   N_2
                                                                          RF
                                                                                                      가
                1).
                          2
                                               RF power 가
                                                                   thermocouple
                                                                         10cm 가
                                                                                                  가
        diffusion pump
                                         10<sup>-6</sup>Torr,
                                                                          800
                                                                                                 가
           . RF
                                                     600W
                                                                                  CF_4
                                                                                                 O_2
99.999%
                                                                                      100sccm
                                                                         1sccm
                                     16054cm3
                                                                                           pellet
    0.35mm 가
                                                                                     polishing
                                                                   600
                                                          200
                                                                       20
                                                                                                     가
                          10<sup>-5</sup> g
                                             가
                                                             electro-micro balance
1.6×10<sup>-6</sup> Torr
                                                                                                  CF_4
                                                                                                          O_2
                               10sccm
                                                                        4:1
                    40sccm
0.3 Torr
                                              RF Power
                                                             100 W
0~6sccm
                                                                                              OES
                                 가
                                                        optical fiber
                                                        가 , F
                                                                                                    703.7nm
                                                                                          peak
     60
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III.

가

 $CF_4+O_2$ 4:1, 300 , RF power  $100\,\mathrm{W}$  $N_2$ 가 0, 3, 5, 7, 10 % , F(703.7nm) 가 monolayers Molecular Layer Etching Rate  $=\frac{N_a/M}{(N_a \mathbf{r}/M)^{2/3}} \frac{x}{A} \frac{1}{t}$  (monolayers/min) x =(g) A = $(cm^2)$ (min)  $Na = 6.022045 \times 10^{23} \text{ (/mol)}$  $= 10.96(g/cm^3)$ M=270.03(g/mol)3 290 , 100 min, RF power 100 W  $N_2$ 가 가 20 %  $O_2$ ,  $CF_4+O_2$ RF power가 100 W normalize 5%가 가 F 가 가  $N_2$ etchant F 가 가 가 10  $CF_4 + O_2(4:1)$ 가 F 가  $CF_4+O_2$  $N_2$ 가 가 , CF<sub>4</sub>+O<sub>2</sub> 4:1  $N_2$ emission intensity OES F(703.7nm)  $N_2$ 가 F atom intensity 5% 가 가

99.9% . , CF<sub>4</sub>+O<sub>2</sub> 3 (Ar He)

가 가 .

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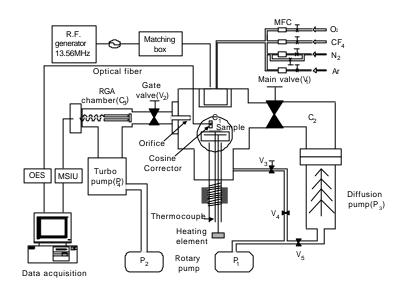
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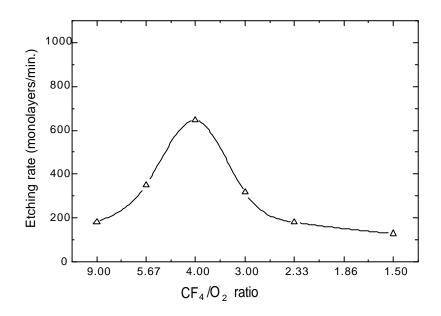
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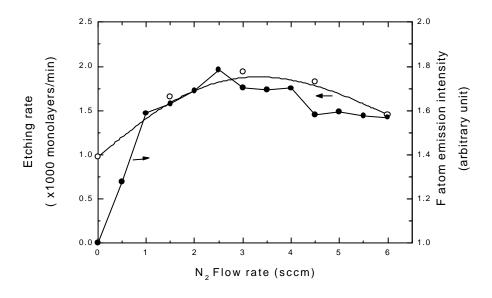


1.





3.  $CF_4+O_2$  Plasma  $O_2$  mole fraction 100 W, 290



4.  $N_2$  7 F atom Intensity 100 W, 300